



Product Specification

G101EAN01.0

AU OPTRONICS CORPORATION

() Preliminary Specifications

(V) Final Specifications

Module	10.1"(10.01") WXGA 16:10 Color TFT-LCD
Model Name	G101EAN01.0
Note	LED Backlight without driving circuit design

<table><tr><td>Customer</td><td>Date</td></tr><tr><td>_____</td><td>_____</td></tr><tr><td>Checked & Approved by</td><td></td></tr><tr><td>_____</td><td>_____</td></tr></table>	Customer	Date	_____	_____	Checked & Approved by		_____	_____	<table><tr><td>Approved by</td><td>Date</td></tr><tr><td>Grace Hung</td><td>2020/12/04</td></tr><tr><td>Prepared by</td><td></td></tr><tr><td>Kevin Tseng</td><td>2020/12/04</td></tr></table>	Approved by	Date	Grace Hung	2020/12/04	Prepared by		Kevin Tseng	2020/12/04
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Note: This Specification is subject to change without notice.	General Display Business Division / AU Optronics corporation																



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Record of Revision

[illegible]

1. Operating Precautions

- 1) Since front polarizer is easily damaged, please be cautious and not to scratch it.
- 2) Be sure to turn off power supply when inserting or disconnecting from input connector.
- 3) Wipe off water drop immediately. Long contact with water may cause discoloration or spots.
- 4) When the panel surface is soiled, wipe it with absorbent cotton or soft cloth.
- 5) Since the panel is made of glass, it may be broken or cracked if dropped or bumped on hard surface.
- 6) To avoid ESD (Electro Static Discharge) damage, be sure to ground yourself before handling TFT-LCD Module.
- 7) Do not open nor modify the module assembly.
- 8) Do not press the reflector sheet at the back of the module to any direction.
- 9) In case if a module has to be put back into the packing container slot after it was taken out from the container, do not press the center of the LED light bar edge. Instead, press at the far ends of the LED light bar edge softly. Otherwise the TFT Module may be damaged.
- 10) At the insertion or removal of the Signal Interface Connector, be sure not to rotate nor tilt the Interface Connector of the TFT Module.
- 11) TFT-LCD Module is not allowed to be twisted & bent even force is added on module in a very short time. Please design your display product well to avoid external force applying to module by end-user directly.
- 12) Small amount of materials having no flammability grade is used in the LCD module. The LCD module should be supplied by power complied with requirements of Limited Power Source (IEC60950 or UL1950), or be applied exemption.
- 13) Severe temperature condition may result in different luminance, response time and lamp ignition voltage.
- 14) Continuous operating TFT-LCD display under low temperature environment may accelerate lamp exhaustion and reduce luminance dramatically.
- 15) Continuous displaying fixed pattern may induce image sticking. It's recommended to use screen saver or shuffle content periodically if fixed pattern is displayed on the screen.
- 16) Disconnecting power supply before handling LCD modules, it can prevent electric shock, DO NOT TOUCH the electrode parts, cables, connectors and LED circuit part of TFT module that a LED light bar build in as a light source of back light unit. It can prevent electrostatic breakdown.

2. General Description

G101EAN01.0 is a Color Active Matrix Liquid Crystal Display composed of a TFT LCD panel, a driver circuit, and LED backlight system. The screen format is intended to support the 16:10 WXGA, 800(H) x1280(V) screen and 16.7M colors (Real 8 bits) without LED backlight driving circuit. All input signals are MIPI interface compatible.

G101EAN01.0 is designed for a display unit of notebook style personal computer and industrial machine.

G101EAN01.0 is a RoHS product.

2.1 Display Characteristics

The following items are characteristics summary on the table under 25 °C condition:

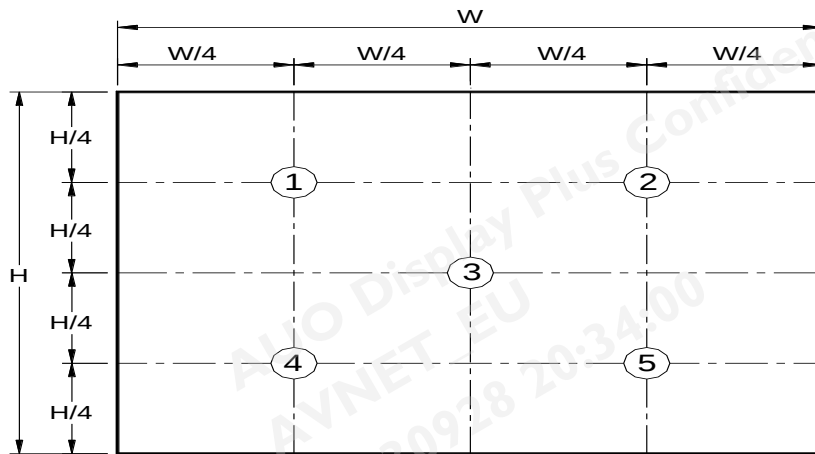
Items	Unit	Specifications			
Screen Diagonal	[mm]	255.397			
Active Area	[mm]	135.36(H) x 216.576(V)			
Pixels H x V		800 x 3(RBG) x 1280			
Pixel Pitch	[mm]	0.1692 X 0.1692			
Pixel Format		R.G.B. Vertical Stripe			
Display Mode		AHVA, Normally Black			
White Luminance	[cd/m2]	350 typ. (center point)			
Luminance Uniformity	δ _{5P}	5P Max. 1.25			
Contrast Ratio		Typ. 1000:1, min 800:1			
Response Time	[ms]	Typ.30			
Nominal Input Voltage VDD	[Volt]	VDD=3.3V typ. / IOVCC=1.8V typ.			
Power Consumption	[Watt]	Logic: 0.4 W @ full white pattern BLU: 1.82 W max (1.76 W typ). , w/o effi.			
Weight	[Grams]	161 g Max			
Physical Size	[mm]		Min	Typ	Max
		Length		232.43	
		Width		150.3	
		Thickness	---	---	2.65 (Panel side) 4.8 (PCBA side)
Electrical Interface		MIPI			
Surface Treatment		Anti Glare			
Support Color		16.7M colors (Real 8 bits)			
Temperature Range	[°C]	0 to +50			
Operating Storage (Non-Operating)		-20 to +60			
RoHS Compliance		RoHS Compliance			

2.2 Optical Characteristics

The optical characteristics are measured under stable conditions at 25 °C (Room Temperature):

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	Note
White Luminance		Center Point	300	350	---	cd/m ²	1, 3, 4.
Viewing Angle	θ_R	Horizontal (Right)	80	85	---	degree	3, 8
	θ_L	Horizontal (Left)	80	85	---		
	ψ_H	Vertical (Upper)	80	85	---		
	ψ_L	Vertical (Lower)	80	85	---		
Luminance Uniformity	%	5 Points	80	---	---		1, 2, 3
Contrast Ratio	CR		800	1000	---		3, 5
Cross talk	%		---	---	2		3, 6
Response Time	T _{RT}	Rising + Falling	---	30	35	msec	3, 7
Color / Chromaticity Coordinates	Red	R _x	0.578	0.608	0.638	CIE 1931	3
		R _y	0.325	0.355	0.385		
	Green	G _x	0.309	0.339	0.369		
		G _y	0.568	0.598	0.628		
	Blue	B _x	0.125	0.155	0.185		
		B _y	0.057	0.087	0.117		
	White	W _x	0.270	0.300	0.330		
		W _y	0.290	0.320	0.350		
			55	60			
NTSC		%					

Note 1: 5 points position (Ref: Active area)

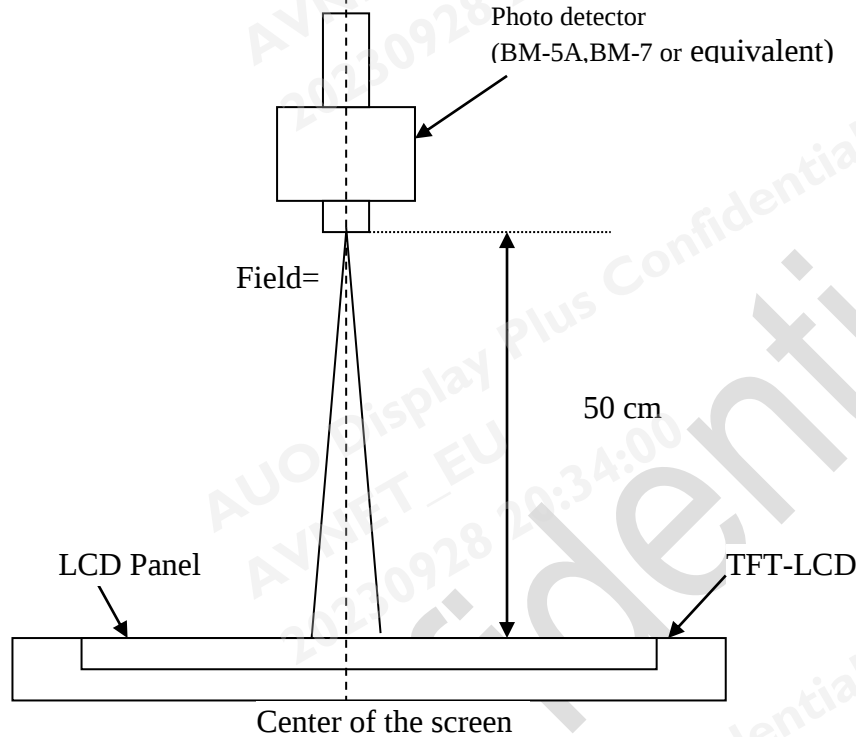


Note 2: The luminance uniformity of 5 points is defined as minimum luminance divided by the maximum luminance values:

$$\delta_{w5} = \frac{\text{Minimum Brightness of five points}}{\text{Maximum Brightness of five points}}$$

Note 3: Measurement method

The LCD module should be stabilized at given temperature for 30 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 30 minutes in a stable, windless and dark room, and it should be measured in the center of screen.



Note 4 : Definition of Average Luminance of White (Y_L):

Measure the luminance of gray level 63 at 5 points , $Y_L = [L(1) + L(2) + L(3) + L(4) + L(5)] / 5$
 $L(x)$ is corresponding to the luminance of the point X at Figure in Note (1).

Note 5 : Definition of contrast ratio:

Contrast ratio is calculated with the following formula.

$$\text{Contrast ratio (CR)} = \frac{\text{Brightness on the "White" state}}{\text{Brightness on the "Black" state}}$$

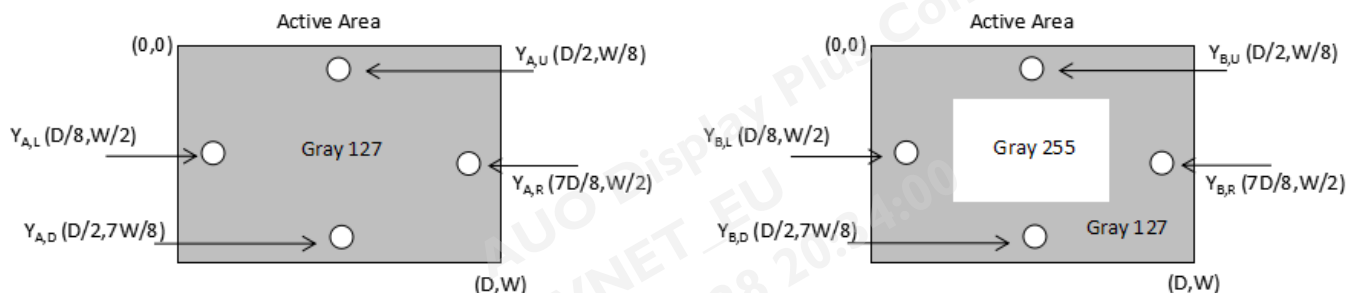
Note 6 : Definition of Cross Talk (CT)

$$CT = |Y_B - Y_A| / Y_A \times 100 (\%)$$

Where

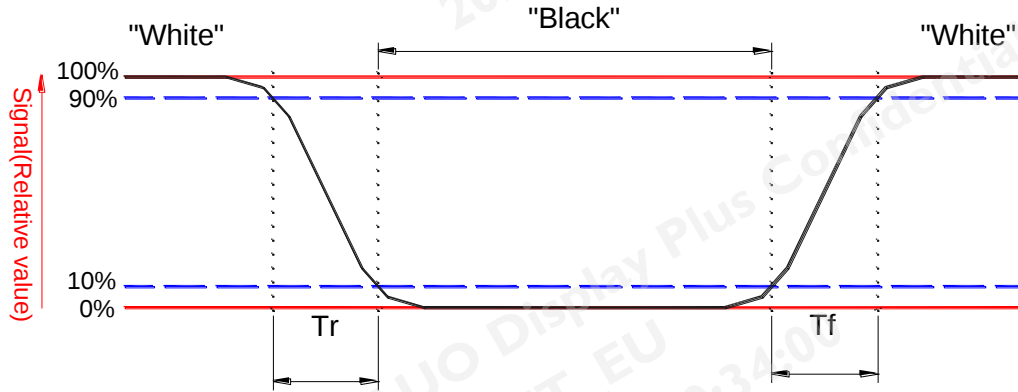
Y_A = Luminance of measured location without gray level 255 pattern (cd/m²)

Y_B = Luminance of measured location with gray level 255 pattern (cd/m²)



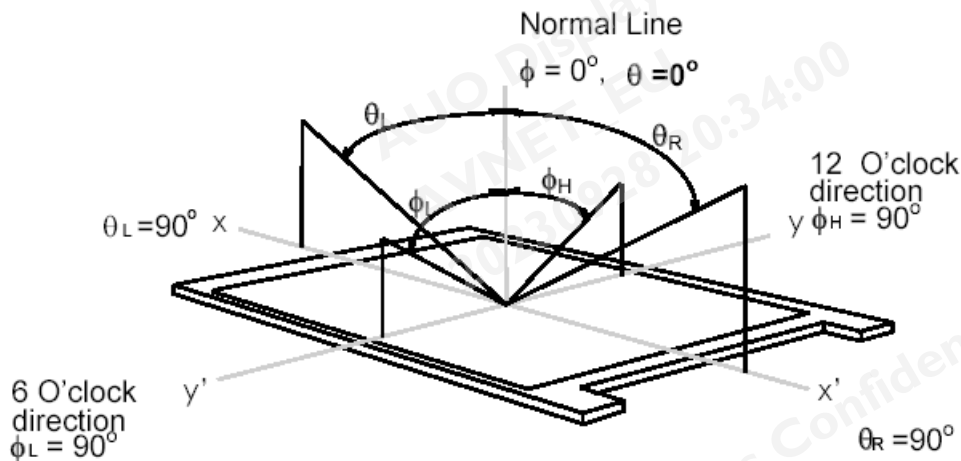
Note 7: Definition of response time:

The output signals of BM-7 or equivalent are measured when the input signals are changed from "Black" to "White" (falling time) and from "White" to "Black" (rising time), respectively. The response time interval between the 10% and 90% of amplitudes. Refer to figure as below.



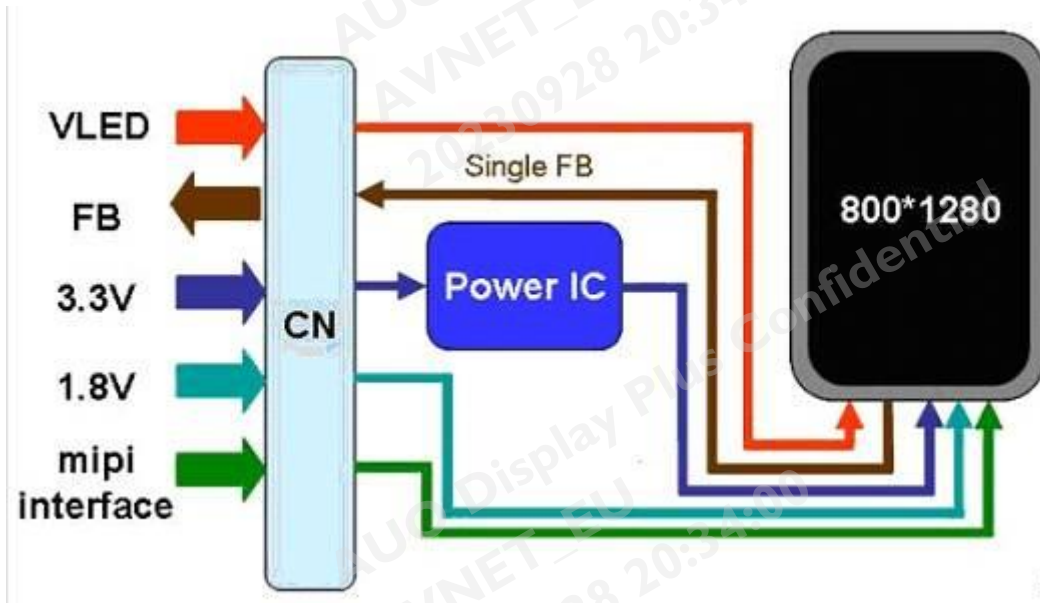
Note 8. Definition of viewing angle

Viewing angle is the measurement of contrast ratio ≥ 10 , at the screen center, over a 180° horizontal and 180° vertical range (off-normal viewing angles). The 180° viewing angle range is broken down as follows; 90° (θ) horizontal left and right and 90° (ϕ) vertical, high (up) and low (down). The measurement direction is typically perpendicular to the display surface with the screen rotated about its center to develop the desired measurement viewing angle.



3. Functional Block Diagram

The following diagram shows the functional block of the 10.1 inches wide Color TFT/LCD 39 Pin one channel Module



4. Absolute Maximum Ratings

An absolute maximum rating of the module is as following:

4.1 Absolute Ratings of TFT LCD Module

Item	Symbol	Min	Max	Unit	Conditions
Logic/LCD Drive Voltage	V _{in}	-0.3	+4.0	[Volt]	Note 1,2

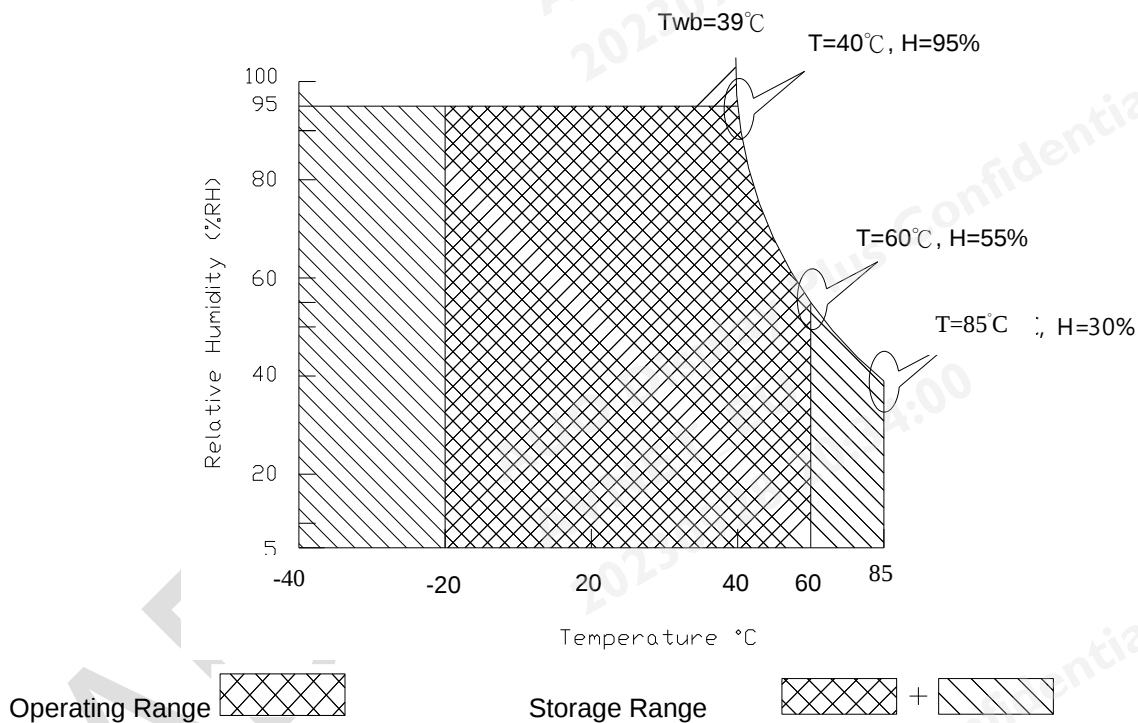
4.2 Absolute Ratings of Environment

Item	Symbol	Min	Max	Unit	Conditions
Operating Temperature	TOP	0	+50	[°C]	Note 3
Operation Humidity	HOP	5	95	[%RH]	Note 3
Storage Temperature	TST	-20	+60	[°C]	Note 3
Storage Humidity	HST	5	95	[%RH]	Note 3

Note 1: At T_a (25°C)

Note 2: Permanent damage to the device may occur if exceed maximum values

Note 3: For quality performance, please refer to AUO IIS (Incoming Inspection Standard).



5. Electrical Characteristics

5.1 TFT LCD Module

5.1.1 Power Specification

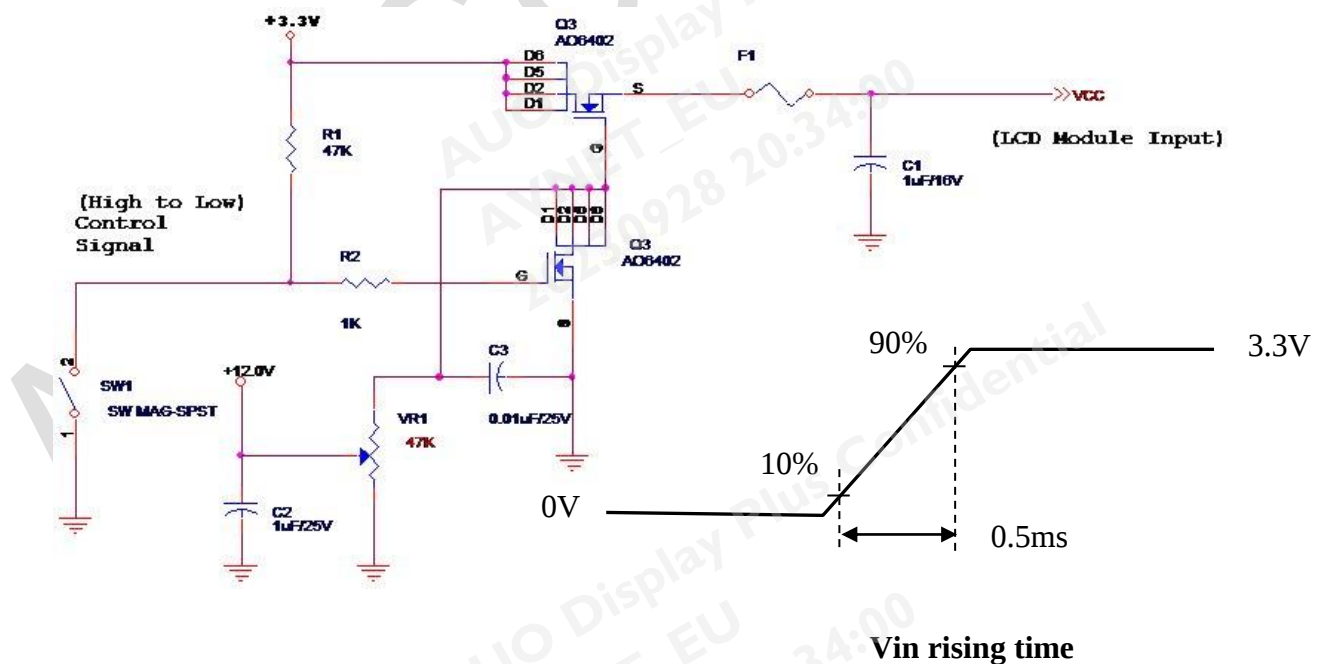
Input power specifications are as follows. The power specification are measured under 25°C and frame frequency under 60Hz

Symble	Parameter	Min	Typ	Max	Units	Note
IOVCC	Logic/LCD Drive Voltage	1.7	1.8	1.9	[Volt]	
P _{IOVCC}	IOVCC Power	-	-	0.054	[Watt]	
I _{IOVCC}	IOVCC Current(RMS)	-	30	-	[mA]	

Symble	Parameter	Min	Typ	Max	Units	Note
VDD	Logic/LCD Drive Voltage	3.0	3.3	3.6	[Volt]	
P _{VDD}	VDD Power	-	-	0.4	[Watt]	Note 1
I _{VDD}	VDD Current(RMS)	-	121	-	[mA]	
IRush	Inrush Current	-	-	1500	[mA]	Note 2
VDDrp	Allowable Logic/LCD Drive Ripple Voltage	-	-	100	[mV] p-p	

Note 1 : Maximum Measurement Condition : White Pattern at 3.3V driving voltage.

Note 2 : Measure Condition

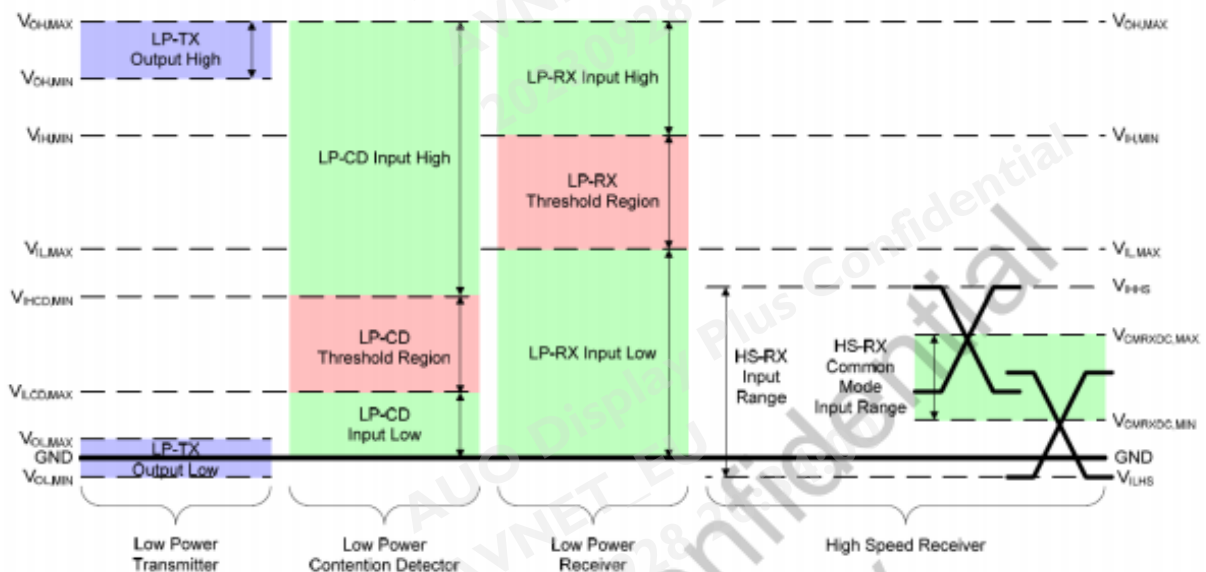


5.1.2 Signal Electrical Characteristics

Input signals shall be low or High-impedance state when VDD is off.

MIPI DC characteristics are as follows:

Parameter	Symbol	Conditions	Specification			Unit
			MIN	TYP	MAX	
Power supply voltage for MIPI Interface						
Power supply voltage for MIPI interface	VDDAM	-	1.75	2.8	6.0	V
	LVDSVDD	-	1.15	1.2	1.375	V
LPDT Input Characteristics						
Pad signal voltage range	VI	-	-50	-	1350	mV
Ground Shift	VGND _{SH}	-	-50	-	50	mV
Logic 0 input threshold	VIL	-	0	-	550	mV
Logic 1 input threshold	VIH	-	880	-	LVDSVDD	mV
Input hysteresis	VHYST	-	25	-	-	mV
LPDT Output Characteristics						
Output low level	VOL	-	-50	-	50	mV
Output high level	VOH	-	1.1	1.2	1.3	V
Logic 1 contention threshold	VIH _{CD,MIN}	-	450	-	LVDSVDD	mV
Logic 0 contention threshold	VIL _{CD,MAX}	-	0	-	200	mV
Output impedance of LPDT	ZOLP	-	80	100	125	ohm
Hi-speed Input/Output Characteristics						
Single-end input low voltage	VIL _{HS}	-	-40	-	-	mV
Single-end input high voltage	VIH _{HS}	-	-	-	460	mV
Common mode voltage	VCM _{RXDC}	-	70	-	330	mV
Hi-speed transmit voltage	VOD	-	140	200	250	mV
Differential input impedance	ZID	-	80	100	125	ohm



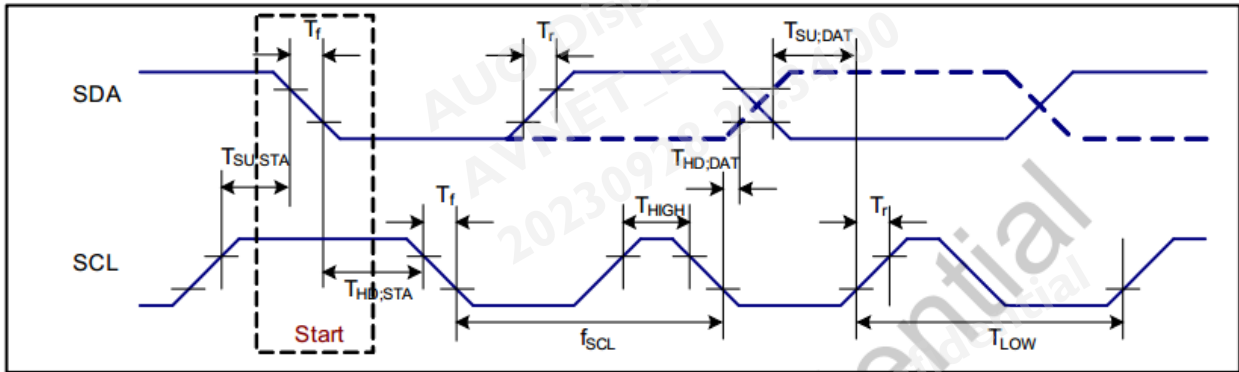


Table: I2C Interface Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{SCLK}	SCL clock frequency	-	DC	-	400	KHz
T_{LOW}	SCL clock LOW period	-	1.3	-	-	#s
T_{HIGH}	SCL clock HIGH period	-	0.6	-	-	#s
$T_{SU,DAT}$	data set-up time	-	100	-	-	ns
$T_{HD,DAT}$	data hold time	-	0	-	0.9	#s
T_r	SCL and SDA rise time	Note 2	$20+0.1C_b$	-	300	ns
T_f	SCL and SDA fall time	Note 2	$20+0.1C_b$	-	300	ns
T_f	SDA fall time for read out	-	$20+0.1C_b$	-	1000	ns
C_b	Capacitive load represented by each bus line	-	-	-	400	pF
$T_{SU,STA}$	Setup time for a repeated START condition	-	0.6	-	-	#s
$T_{HD,STA}$	START condition hold time	-	0.6	-	-	#s
$T_{SU,STO}$	Setup time for STOP condition	-	0.6	-	-	#s
T_{SW}	Tolerable spike width on bus	Note 1	-	-	50	ns
T_{BUF}	BUS free time between a STOP and START condition	-	1.3	-	-	#s

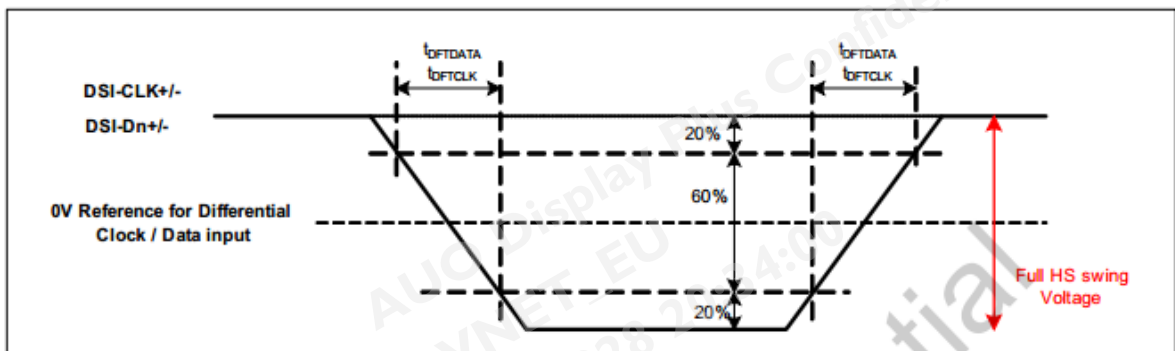
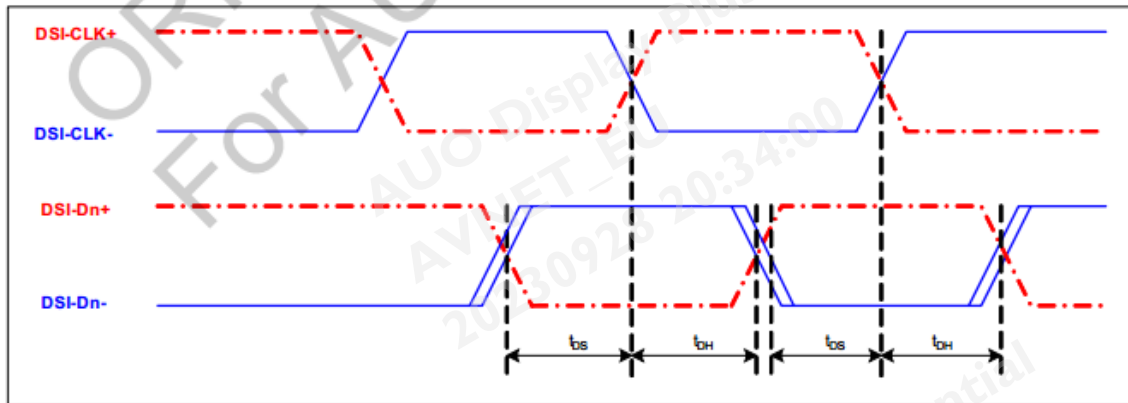
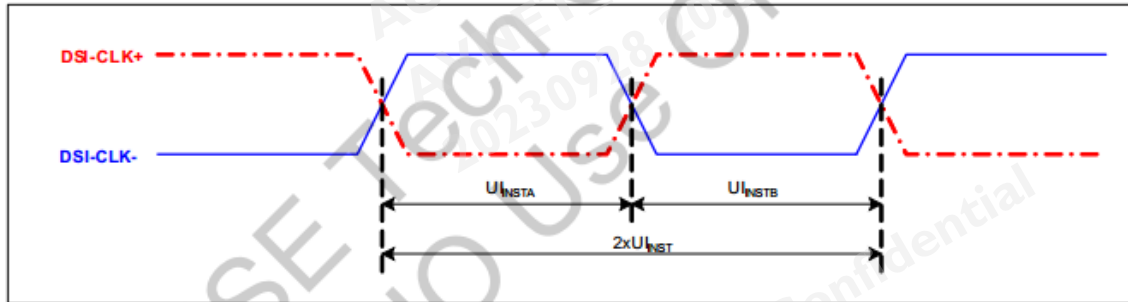
Note1: The device inputs SDA and SCL are filtered and will reject spikes on the bus lines of width $< t_{SW(max)}$.

Note2: The rise and fall times specified here refer to the driver device and are part of the general fast I²C-bus specification. C_b = capacitive load per bus line.

Note3: All timing values are valid within the operating supply voltage and ambient temperature ranges and are referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DDI}

MIPI High-Speed Data-clock Timing

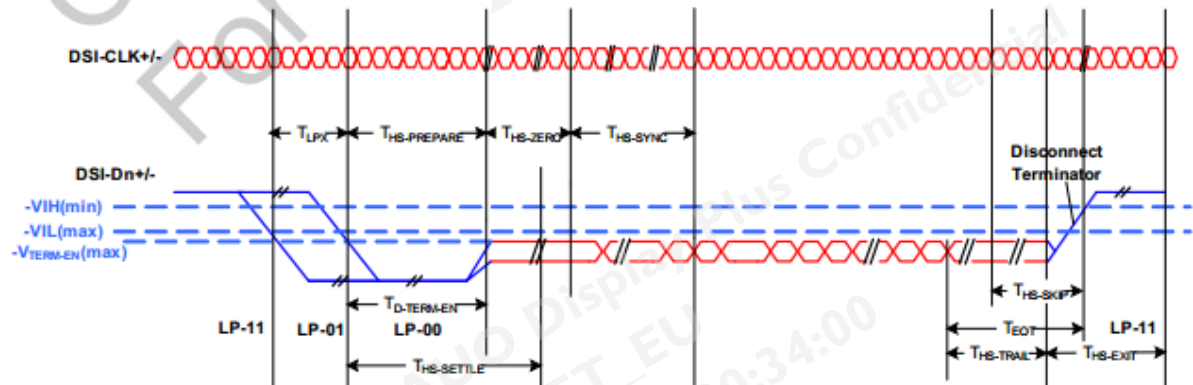
Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Mode						
DSI-CLK+/-	2xUI _{INST}	Double UI instantaneous	2.22	-	25	ns
DSI-CLK+/-	UI _{INSTA} , UI _{INSTB}	UI instantaneous Halfs	1.11	-	12.5	ns
DSI-Dn+/-	t _{DS}	Data to clock setup time	0.15	-	-	UI
DSI-Dn+/-	t _{DH}	Data to clock hold time	0.15	-	-	UI
DSI-CLK+/-	t _{DRTCLK}	Differential rise time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DRTDATA}	Differential rise time for data	150	-	0.3UI	ps
DSI-CLK+/-	t _{DFTCLK}	Differential fall time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DFTDATA}	Differential fall time for data	150	-	0.3UI	ps



The timing definitions are listed in below:

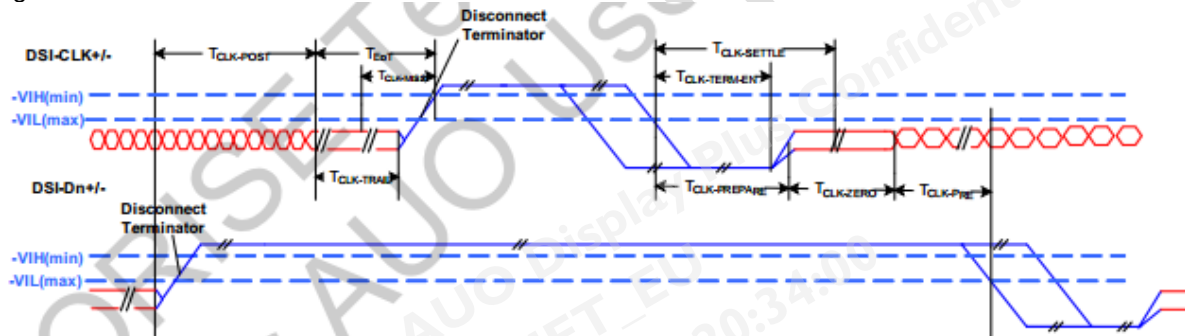
Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Data Transmission Bursts						
DSI-Dn+/-	T _{LPX}	Length of any low-power state period	50	-	-	ns
DSI-Dn+/-	T _{HS-PREPARE}	Time to drive LP-00 to prepare for HS transmission	40ns + 4UI	-	85ns + 6UI	ns
DSI-Dn+/-	T _{HS-PREPARE} + T _{HS-ZERO}	T _{HS-PREPARE} + time to drive HS-0 before the sync sequence	145ns + 10UI	-	-	ns
DSI-Dn+/-	T _{D-TERM-EN}	Time to enable Data Lane receiver line termination measured from when Dn crosses V _{IL(max)}	Time for Dn to reach V _{TERM-EN}	-	35ns + 4UI	ns
DSI-Dn+/-	T _{HS-SKIP}	Time-out at RX to ignore transition period of EoT	40	-	55ns + 4UI	ns
DSI-Dn+/-	T _{HS-TRAIL}	Time to drive flipped differential state after last payload data bit of a HS transmission burst	max (8UI, 60ns+4UI)	-	-	ns
DSI-Dn+/-	T _{HS-EXIT}	Time to drive LP-11 after HS burst	100	-	-	ns
DSI-Dn+/-	T _{EoT}	Time from start of T _{HS-TRAIL} period to start of LP-11 state	-	-	105ns + 12UI	ns

High-Speed Data Transmission in Bursts



Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
Switching the clock Lane between clock Transmission and Low Power Mode						
DSI-CLK+/-	T _{CLK-POST}	Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	60ns + 52UI	-	-	ns
DSI-CLK+/-	T _{CLK-PRE}	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	8	-	-	UI
DSI-CLK+/-	T _{CLK-PREPARE}	Time to drive LP-00 to prepare for HS clock transmission	38	-	95	ns
DSI-CLK+/-	T _{CLK-TERM-EN}	Time to enable Clock Lane receiver line termination measured from when Dn crosses V _{IL(max)}	Time for Dn to reach V _{TERM-EN}	-	38	ns
DSI-CLK+/-	T _{CLK-PREPARE} + T _{CLK-ZERO}	T _{CLK-PREPARE} + time for lead HS-0 drive period before starting Clock	300	-	-	ns
DSI-CLK+/-	T _{CLK-TRAIL}	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	-	ns
DSI-CLK+/-	T _{EoT}	Time from start of T _{CLK-TRAIL} period to start of LP-11 state	-	-	105ns + 12UI	ns

Switching the Clock Lane between Clock Transmission and Low-Power Mode





5.2 Backlight Unit

5.2.1 LED characteristic

Following characteristics are measured under a stable condition using an inverter at 25°C (Room Temperature):

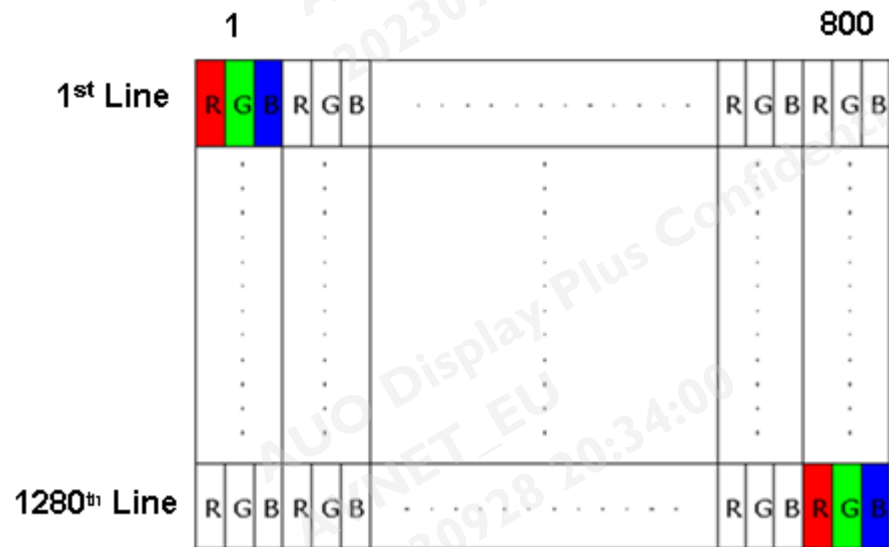
Parameter	Symbol	Min	Typ	Max	Units	Condition
Backlight Power Consumption (W/O Efficiency)	PLED			1.82	[Watt]	Note 1 (Ta= 25°C)
LED Forward Voltage	VF	2.8	3.0	3.2	[Volt]	(Ta= 25°C)
LED Forward Voltage of every LED string	Vf-string	19.6	21	22.4	[Volt]	
LED Forward Current	IF		21		[mA]	(Ta= 25°C)
LED Life time	N/A	≥ 15000			Hour	Note 1 (Ta=25°C)

Note 1: calculator value for reference PLED based on 21 mA

6. Signal Characteristic

6.1 Pixel Format Image

Following figure shows the relationship between input signal and LCD pixel format.



6.2 Integration Interface Requirement

6.2.1 MIPI/TP Connector Description

Physical interface is described as for the connector on module.

These connectors are capable of accommodating the following signals and will be following components.

Connector Name / Designation	For Signal Connector
Manufacturer	Hirose
Type / Part Number	FH35C-39S-0.3SHW
Mating Housing/Part Number	FPC or Compatible

6.2.2 MIPI Pin Assignment

MIPI is a differential signal technology for LCD interface and high speed data transfer device.

Pin No.	Symbol	Description	I/O
1	NC	NC	-
2	NC	NC	-
3	NC	NC	-
4	FB4	LED-	P
5	FB3	LED-	P
6	FB2	LED-	P
7	FB1	LED-	P
8	NC	NC	-
9	VLED	LED+	P
10	VLED	LED+	P
11	VLED	LED+	P
12	NC	7.5V For VPP	-
13	LED PWMIn	NC	I
14	LED PWMOut	LED PWMOut 1.8v	O
15	ID	ID(GND for AUO)	I/O
16	LCD_RST	Reset	I
17	NC	NC	-
18	NC	NC	-
19	VDD	3.3V	P
20	VDD	3.3V	P
21	VDD	3.3V	P
22	IOVCC	1.8V	P
23	IOVCC	1.8V	P
24	GND	GND	P
25	D3P	MIPI Input Data Pair D3P	I
26	D3N	MIPI Input Data Pair D3N	I
27	GND	GND	P
28	D2P	MIPI Input Data Pair D2P	I
29	D2N	MIPI Input Data Pair D2N	I
30	GND	GND	P
31	CLKP	MIPI Input Data Pair CLKP	I
32	CLKN	MIPI Input Data Pair CLKN	I
33	GND	GND	P
34	D1P	MIPI Input Clock Pair D1P	I
35	D1N	MIPI Input Clock Pair D1N	I
36	GND	GND	P
37	D0P	MIPI Input Data Pair D0P	I
38	D0N	MIPI Input Data Pair D0N	I
39	GND	GND	I

6.3 MIPI Interface Timing

6.3.1 Timing Characteristics

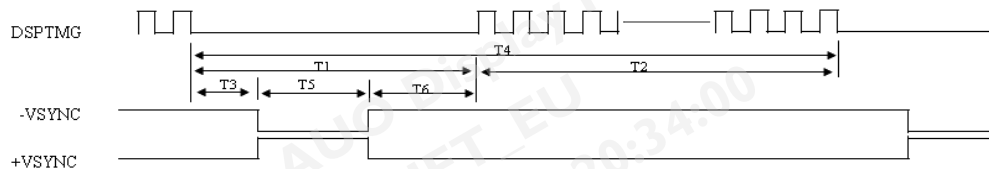
Basically, interface timings should match the 800 x 1280 /60 Hz manufacturing guide line timing.

Vertical Total	VT (tv)	1300	line
Vertical Front-Porch	VFP (tvfp)	8	line
Vertical Active	VA (tvd)	1280	line
Vertical Sync.	VS (twv)	4	line
Vertical Back-Porch	VBP (tvbp)	8	line
Horizontal Total	HT (th)	960	clk(pixel)
Horizontal Front-Porch	HFP (thfp)	24	clk(pixel)
Horizontal Active	HA (thd)	800	clk(pixel)
Horizontal Sync.	HS (thw)	4	clk(pixel)
Horizontal Back-Porch	HBP (thbp)	132	clk(pixel)
Pixel Frequency	CLK (fc)	75.00	MHz

Driving

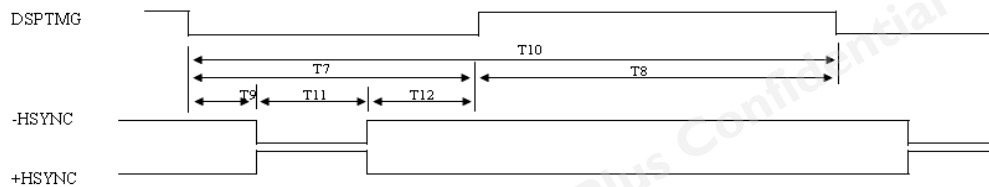
(LVDS Receiver Output)

Vertical Timing



Item	T1 Vertical Blanking	T2 Active Field	T3 VSYNC Front Porch	T4 Frame Time	T5 VSYNC Width	T6 VSYNC Back Porch
Value	20	1280	8	1300	4	8

Horizontal Timing



Item	T7 Horizontal Blanking	T8 Active Field	T9 HSYNC Front Porch	T10 H Line Time	T11 HSYNC Width	T12 HSYNC Back Porch
Value	160	800	24	960	4	132

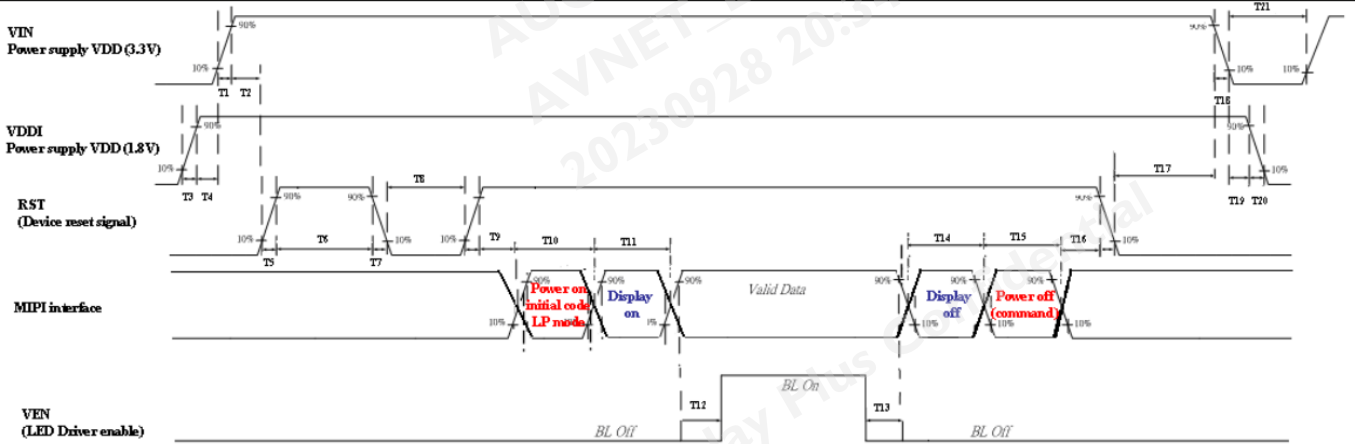
Dot Timing

Item	Dot Clock Frequency	Data Clock Frequency
Value	75MHz	Dot Clock Frequency

6.4 Power ON(Wake Up)/OFF(Stand-by) sequence

6.4.1 Power

Power on/off sequence is as follows. Interface signals and LED on/off sequence are also shown in the chart.



Power Sequence Timing			
Parameter	Value		Units
	Min.	Max.	
T1	0.5	10	ms
T2	1	-	
T3	0.5	10	
T4	0	50	
T5	0	0.002	
T6	1	-	
T7	0	0.002	
T8	0.01	-	
T9	5	-	
T10	180	-	
T11	33.4	-	
T12	200	-	
T13	200	-	
T14	33.4	-	
T15	180	-	
T16	50	-	
T17	120	-	
T18	0	10	
T19	0	10	
T20	0	10	
T21	500	-	

6.4.2 MIPI Command

T10 : power on => initial code + sleep out(0x11) (by panel different)

T11 : display on (0x29)

T14 : display off (0x28)

T15 : power off => sleep in (0x10)

7. Panel Reliability Test

7.1 Vibration Test

Test Spec:

- Test method: Non-Operation
- Acceleration: 1.5 G
- Frequency: 10 - 500Hz Random
- Sweep: 30 Minutes each Axis (X, Y, Z)

7.2 Shock Test

Test Spec:

- Test method: Non-Operation
- Acceleration: 220 G , Half sine wave
- Active time: 2 ms
- Pulse: X,Y,Z .one time for each side

7.3 Reliability Test

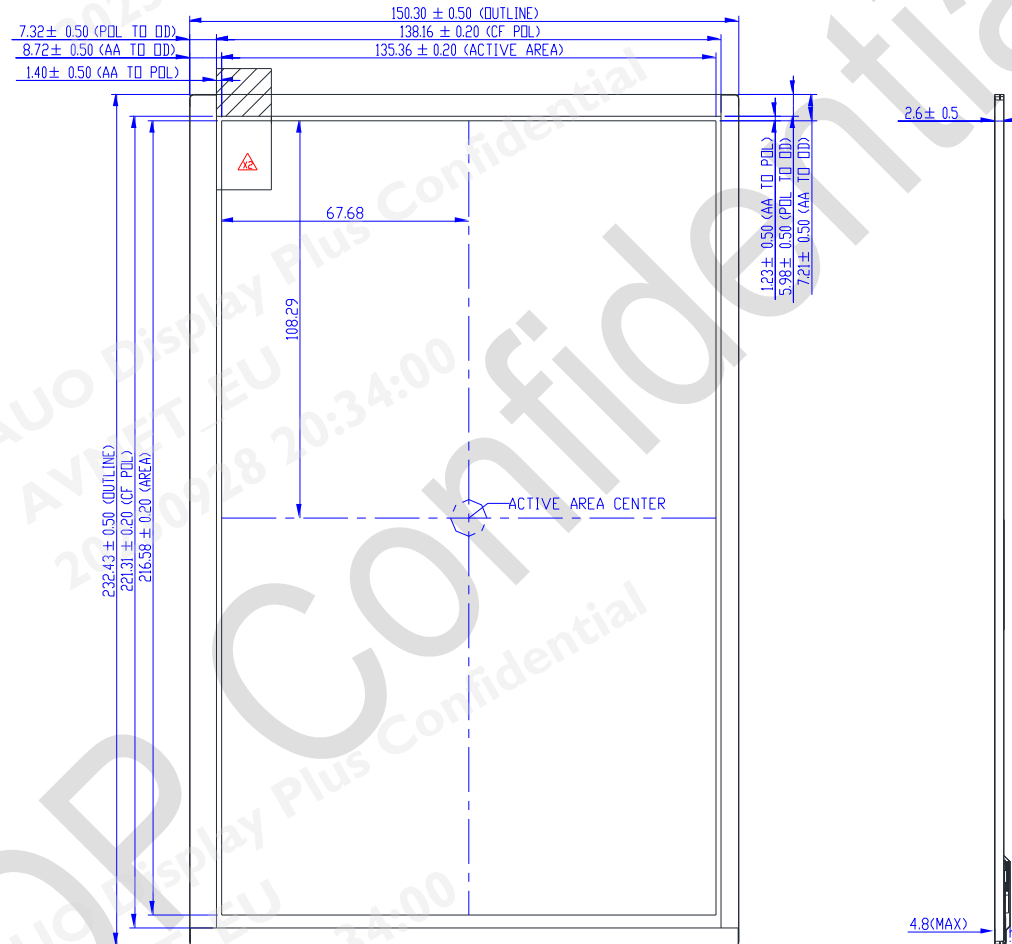
Items	Required Condition	Note
Temperature Humidity Bias	Ta= 40°C , 90%RH, 300h	
High Temperature Operation	Ta= 50°C , Dry, 300h	
Low Temperature Operation	Ta= 0°C , 300h	
High Temperature Storage	Ta= 60°C , 300h	
Low Temperature Storage	Ta= -20°C , 300h	
Thermal Shock Test	Ta=-20°C to 60°C , Duration at 30 min, 100 cycles	
ESD	Contact : ±8 KV Air : ±15 KV	Note 1

Note1: According to EN 61000-4-2 , ESD class B: Some performance degradation allowed. No data lost
Self-recoverable. No hardware failures.

Remark: MTBF (Excluding the LED): 30,000 hours with a confidence level 90%

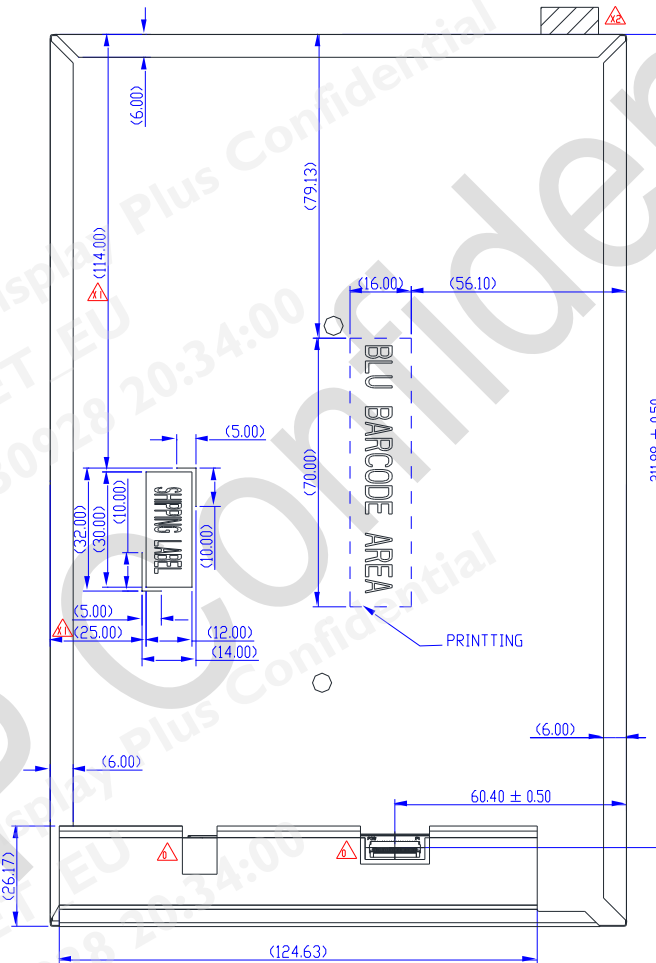
8. Mechanical Characteristics

8.1 LCM Standard Outline Dimension (Front View)



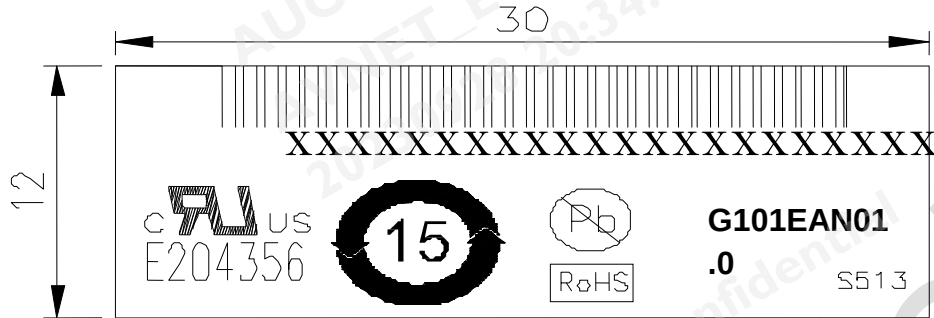
Notes:
1.TOLERANCE IS 0.5mm IF NOT SPECIFIED.
2.Unit:mm

8.2 LCM Standard Outline Dimension (Rear View)



9. Label and Packaging

9.1 Shipping Label (on the rear side of TFT-LCD display)



9.2 Carton Label Format

AU Optronics	QTY : 40	RoHS	Pb
MODEL NO : G101EAN01.0			
PART NO : 97.10G25.000			
CUSTOMER NO :			
CARTON NO :			
Made in China	*ZM100-0652300205*		

9.3 Shipping Package of Palletizing Sequence

Pallet size : 1150mm x 840mm x 138mm

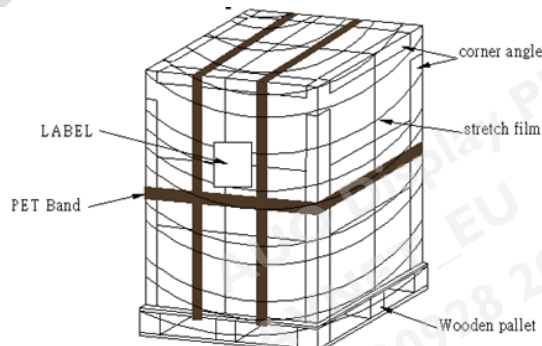
Box stacked_Max

Module by air : (2x2)x3 layers , one pallet put 12 boxes , total 480 pcs module

Module by sea : (2x2)x3 layers + (2x2)x2 layers , two pallet put 20 boxes , total 800 pcs module

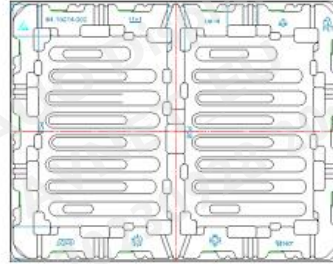
Module by sea_HQ : (2x2)x3 layers + (2x2)x2 layers , two pallet put 20 boxes , total 800 pcs module

Box stacked on pallet (Picture):

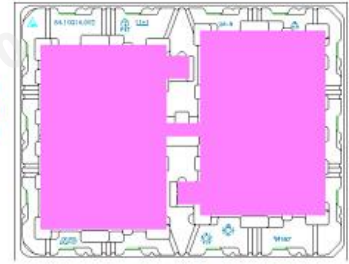
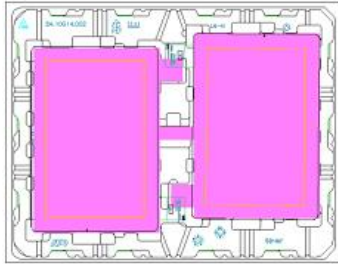
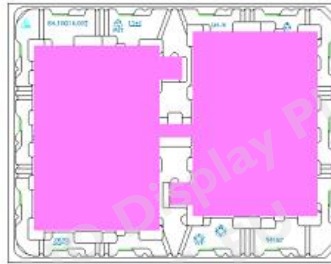
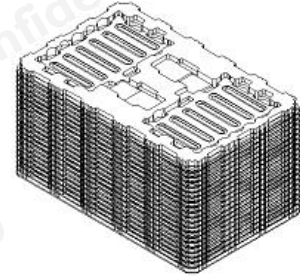




PP Board



1pcs Flat Tray


1pcs tray with
2 pcs EPE Spacer

Put 2 pcs Panel
(Face down)

1pcs Tray with
2pcs Panel+2pcs EPE Spacer

Stack flat tray one by one until 21th
pcs tray, the 21th tray is empty.

Put 40 pcs Panel into
anti-static bag(use tape to fix)


Put EPE cushion into carton


Then put anti-static bag into carton
which has EPE cushion in it


Put on top EPE cushion



And use tape to fix carton